Typical Application Circuit (Multiple Daisy Chained TLC5957s)
Connects to MSP-EXP432P401R
You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.

### Variant/Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

**Assembly Notes**

- **ZZ1**
  - Assembly Note
  - Not necessary for all PCB labels only

- **ZZ2**
  - Assembly Note
  - These assemblies are ESD sensitive, ESD precautions shall be observed.

- **ZZ3**
  - Assembly Note
  - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

- **ZZ4**
  - Assembly Note
  - These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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